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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: 09/852,824 Filed: May 10, 2001
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: P002-2

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

SECOND PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

In the Claims

Add the following claims:

1 70. The method as recited in claim 15, including attaching the substrate to the
2 chip using an adhesive that does not electrically connect the substrate and the chip.

1 71. The method as recited in claim 15, including attaching the substrate to the
2 chip using an adhesive that is sandwiched between and contacts the substrate and the chip
3 and does not electrically connect the substrate and the chip.

1 72. The method as recited in claim 15, wherein the pad is a bumbleless pad.

1 73. The method as recited in claim 15, wherein the pad is a solder-free pad.